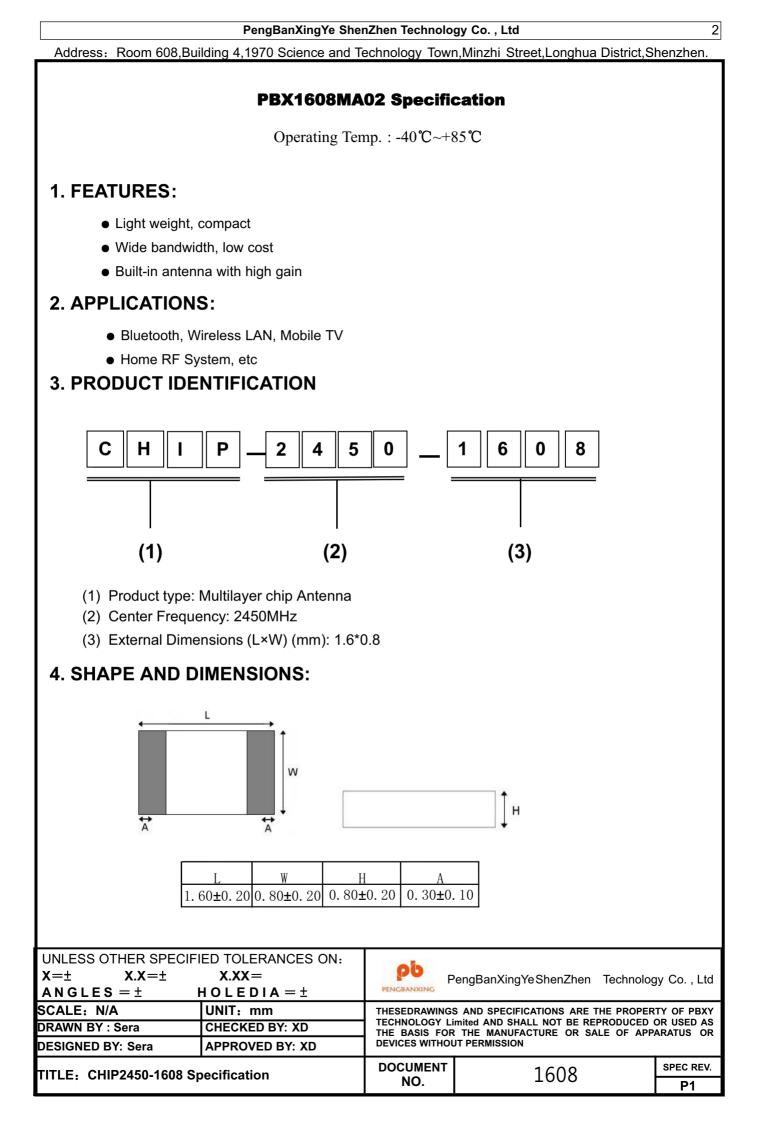
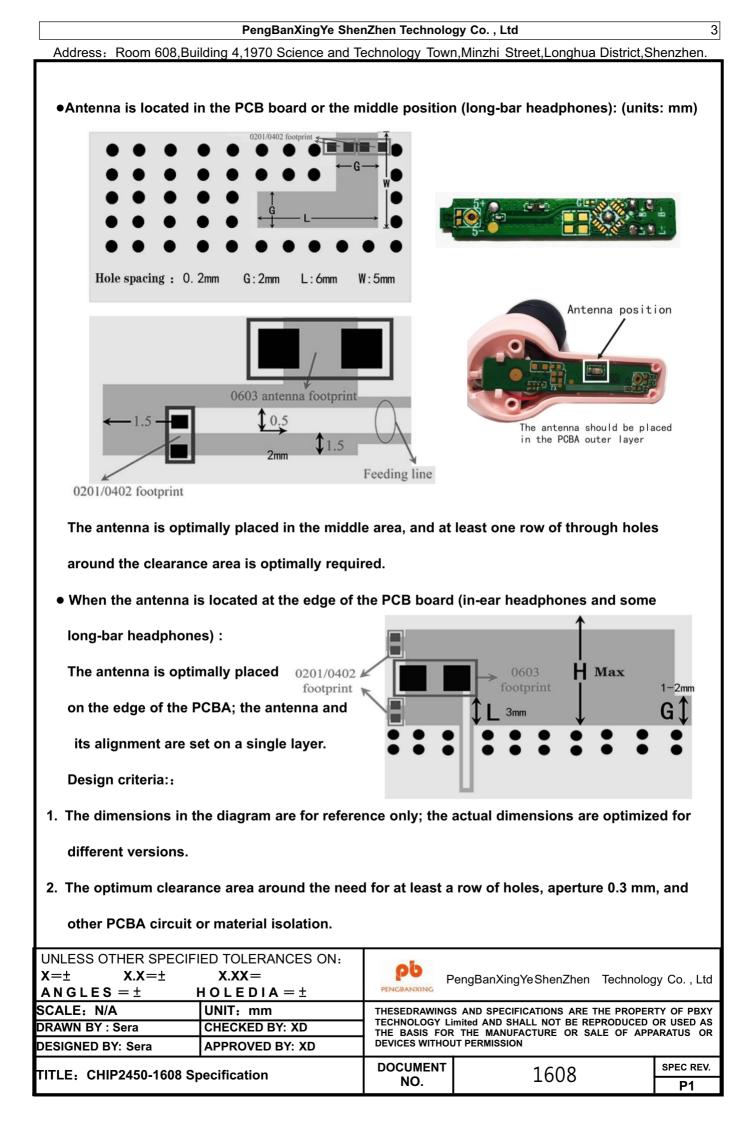
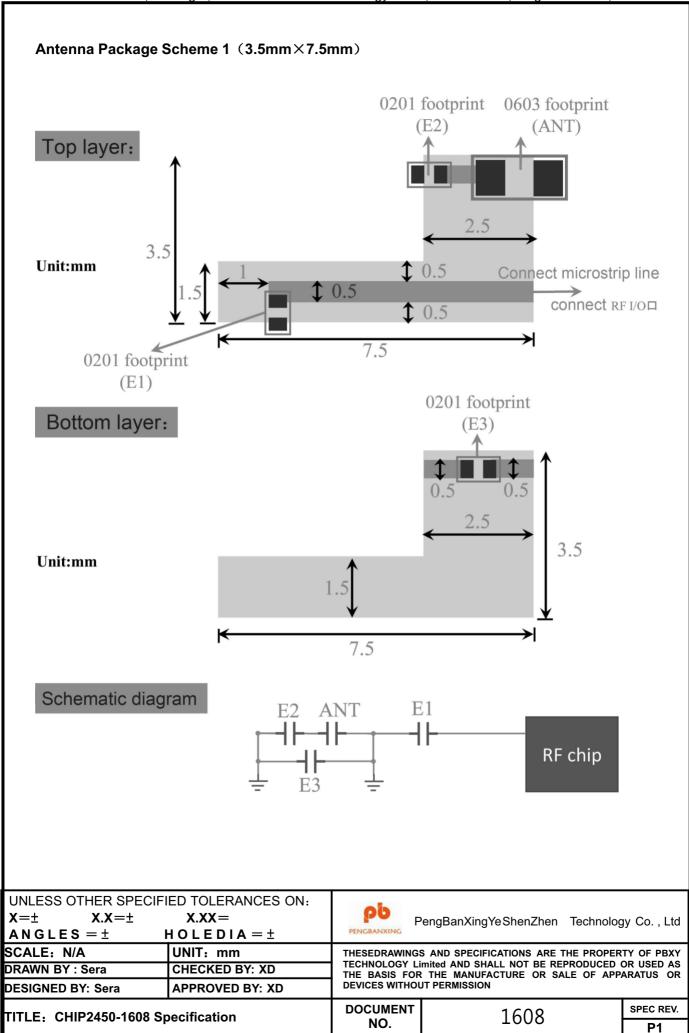
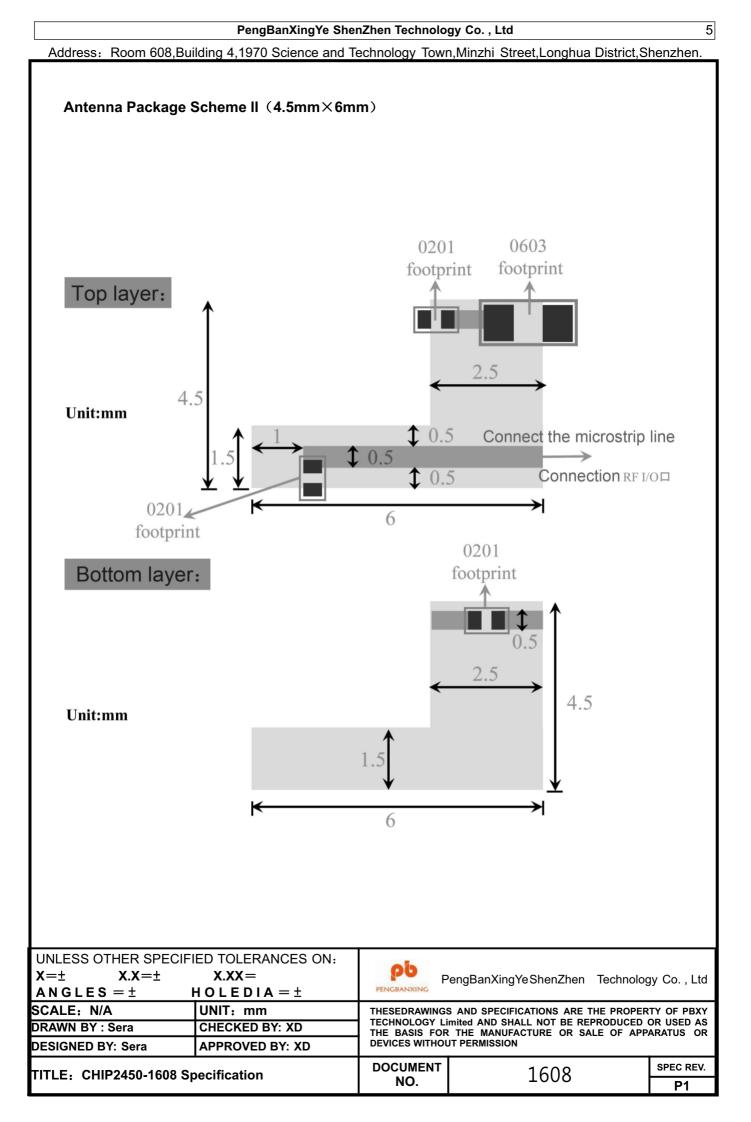
PengBanXingYe ShenZhen Technology Co. , Ltd 1					
Address: Room 608, Building 4, 1970 Science and Technology Town, Minzhi Street, Longhua District, Shenzhen.					
SPECIF	ICATI	ONS			
CUSTOMER:					
DESCRIPTION: <u>Geomag</u>	gnetic An	ntenna			
CUSTOMER PART NO:					
OUR MODEL NO: PBX	(1608MA	02			
DATE:					
PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL" WITH YOUR APPROVED SIGNATURES					
Approved LiuFei Audit	LiuFei	Making	LiuXiaoMei		
Customer Acknowledges Signature					
Date					
UNLESS OTHER SPECIFIED TOLERANCES ON: $X=\pm$ $X.X=\pm$ $X.XX=$ ANGLES = \pm HOLEDIA = \pm	PENGBANXING		henZhen Technolog	-	
SCALE: N/A UNIT: mm DRAWN BY : Sera CHECKED BY: XD DESIGNED BY: Sera APPROVED BY: XD	TECHNOLOGY Li	mited AND SHALL THE MANUFACTU	IONS ARE THE PROPER NOT BE REPRODUCED (JRE OR SALE OF APP)	OR USED AS	
TITLE: CHIP2450-1608 Specification	DOCUMENT NO.	1	608	SPEC REV. P1	

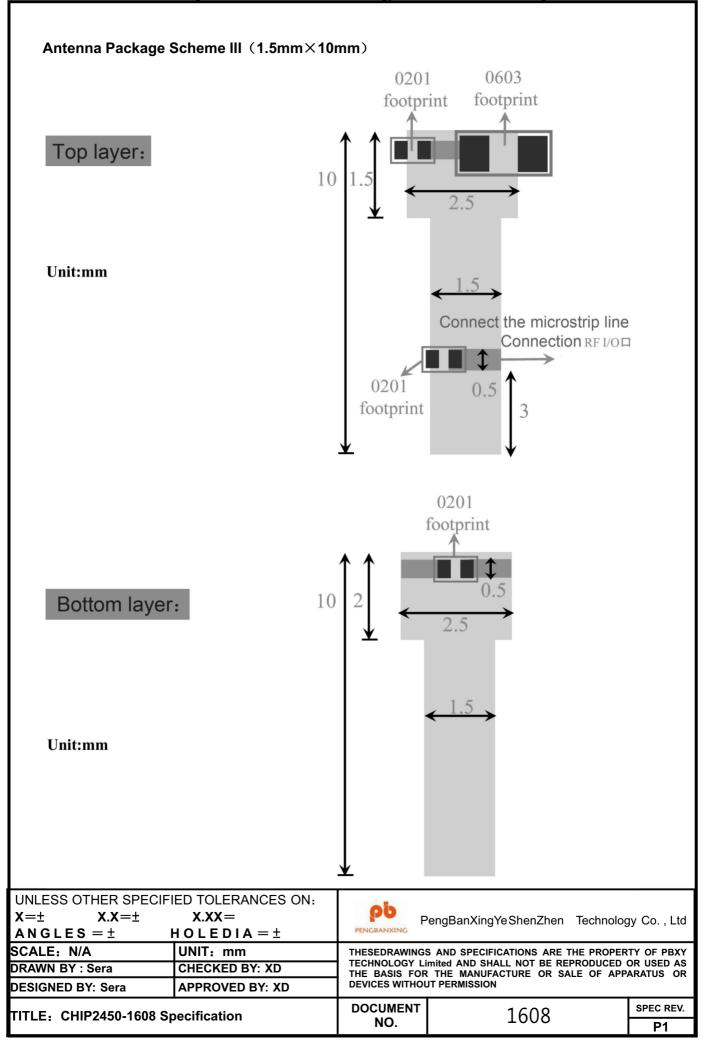




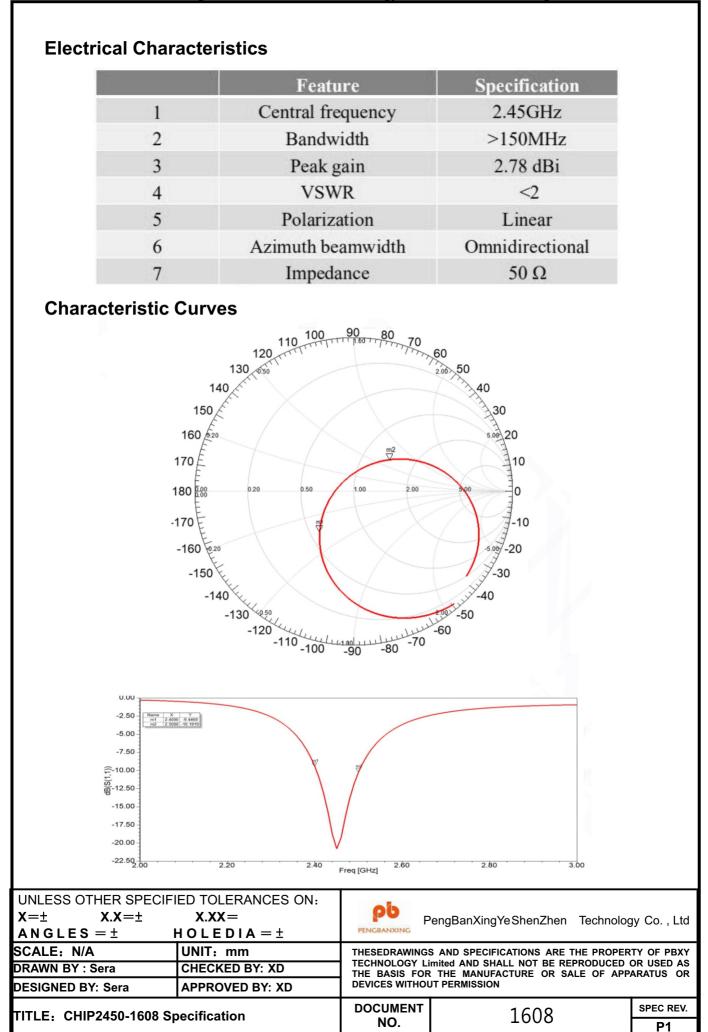
Address: Room 608, Building 4, 1970 Science and Technology Town, Minzhi Street, Longhua District, Shenzhen.

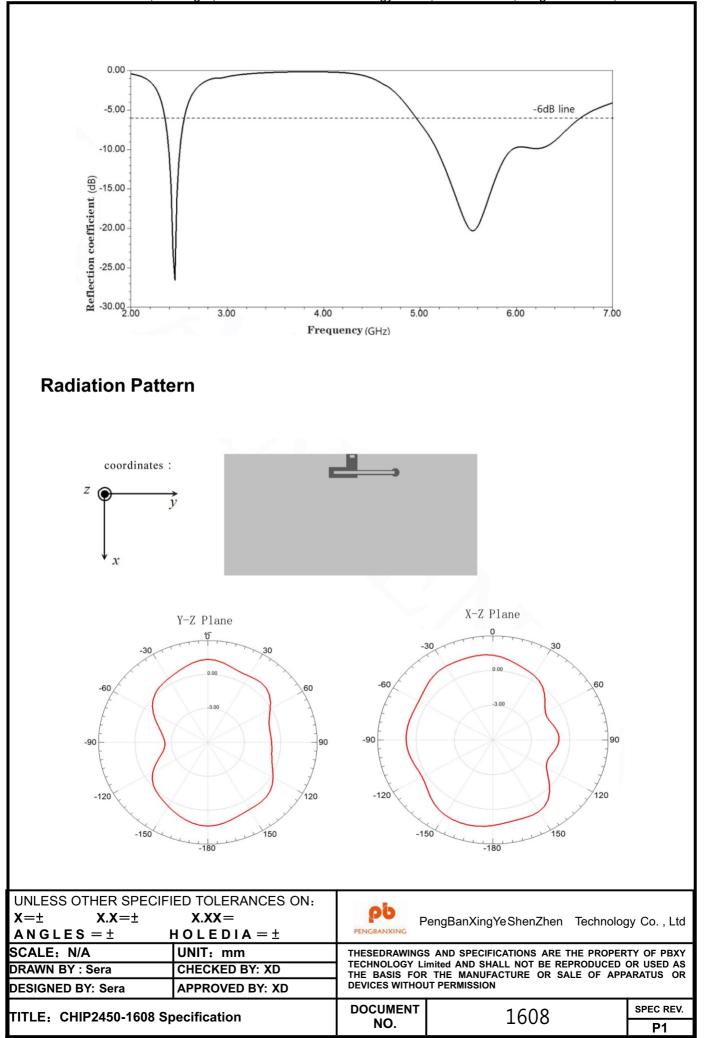


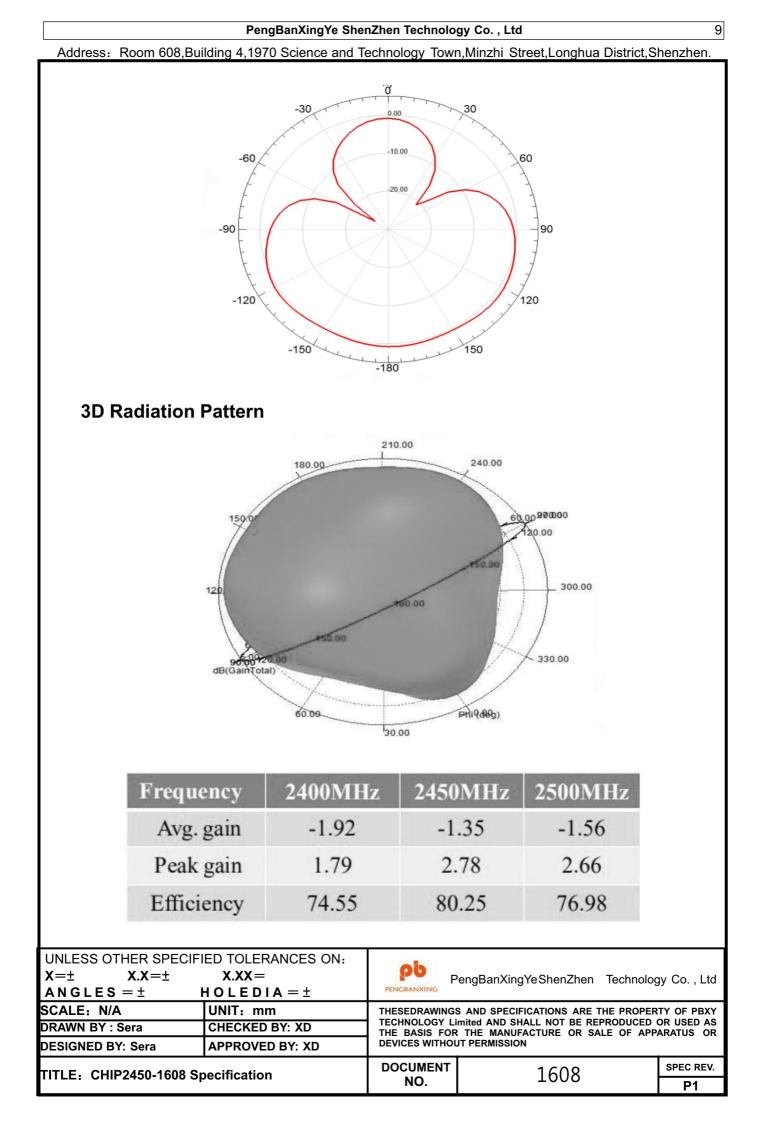




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PengBanXingYe ShenZhen Technology Co., Ltd Address: Room 608,Building 4,1970 Science and Technology Town,Minzhi Street,Longhua District,Shenzhen. Radiation Pattern The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator,a standard horn antenna and Vector Network Analyzer is used to collect data. Image: Control of the table of table. Image: Control of table Image

Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at -40° C $\pm5^{\circ}$ C, 2. Convert to $\pm105^{\circ}$ C (5 minutes) 3. 30 ± 3 minutes at $\pm105^{\circ}$ C $\pm5^{\circ}$ C, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: 85±5°C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	l. Temperature: 150°C±5°C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5℃ 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245 ± 5 °C for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH. The product should be used within 1 year from the time of delivery.

(b) On board:

The temperature should be within -40~85°C and humidity should be less than 85% RH.

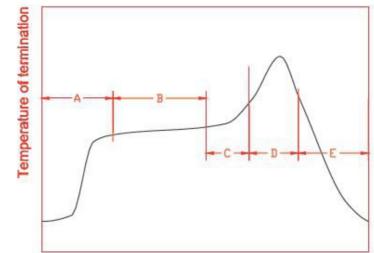
(3) Operating Temperature Range

Operating temperature range : -40 $^\circ\!\mathrm{C}$ to +105 $^\circ\!\mathrm{C}$.

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SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBXY		
DRAWN BY : Sera	CHECKED BY: XD TECHNOLOGY Limited AND SHALL NOT BE REF THE BASIS FOR THE MANUFACTURE OR SAI			
DESIGNED BY: Sera	APPROVED BY: XD	DEVICES WITHOUT PERMISSION		
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8. Recommended Reflow Soldering



		Time	
A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
В	Preheating	140℃ to 160℃	60s to 120s
С	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	$1^{\circ}C/s \sim 4^{\circ}C/s$
	0004 84	A5. 1021	

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- (a) The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

UNLESS OTHER SPECIF $X=\pm$ $X.X=\pm$ ANGLES = \pm	IED TOLERANCES ON: X.XX= HOLEDIA=±	PENGBANXING P	engBanXingYeShenZhen Technolo	gy Co. , Ltd
SCALE: N/A	UNIT: mm	THESEDRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBXY TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED AS		
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TITLE: CHIP2450-1608 Specification		DOCUMENT NO.	1608	SPEC REV.
			1000	P1

